

Description

The AP80P04NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -40V I_{D} = -80 A$

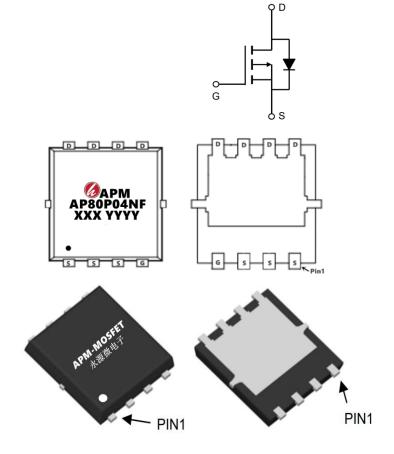
 $R_{DS(ON)} < -10m\Omega$ @ $V_{GS}=-10V$ (Type: 7.0m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP80P04NF	PDFN5*6-8L	AP80P04NF	5000

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	-40	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹ -80		А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-56	А	
Ірм	Pulsed Drain Current ²	-280	А	
EAS	Single Pulse Avalanche Energy ³ 500		mJ	
las	Avalanche Current	-50	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	52.1	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
R ₀ JA	Thermal Resistance Junction-Ambient ¹ 25		°C/W	
Rejc	Thermal Resistance Junction-Case ¹	2.4 °C/W		



Electrical Characteristics (T_J=25℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40	-44		V	
△BVdss/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.023		V/°C	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-12A		7.0	10		
		V _{GS} =-4.5V , I _D =-12A		9.0	15	mΩ	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.8	-2.5	V	
Ipss	Drain-Source Leakage Current	V _{DS} =-40V , V _{GS} =0V , T _J =25°C			1	uA	
IDSS		V _{DS} =-40V , V _{GS} =0V , T _J =55°C			5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-15V , I _D =-12A		20		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		7	14	Ω	
Q_g	Total Gate Charge (-4.5V)			27.9			
Qgs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-10V , I _D =-12A		7.7		nC	
Q_{gd}	Gate-Drain Charge	.5 .=		7.5			
Td(on)	Turn-On Delay Time			40			
Tr	Rise Time	V_{DD} =-20V , V_{GS} =-10V , R_{G} =3.0 Ω .		35.2		no	
Td(off)	Turn-Off Delay Time	I _D =-12A		100		ns	
T _f	Fall Time			9.6			
Ciss	Input Capacitance			6500			
Coss	Output Capacitance	V _{DS} =-20V , V _{GS} =0V , f=1MHz		790		pF	
Crss	Reverse Transfer Capacitance			605			
ls	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			-70	Α	
Vsp	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	٧	

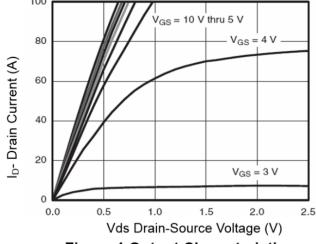
Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$
- $3\$ The EAS data shows Max. rating . The test condition is VDD=-32V,VGS=-10V,L=0.1mH,IAS=-50A
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

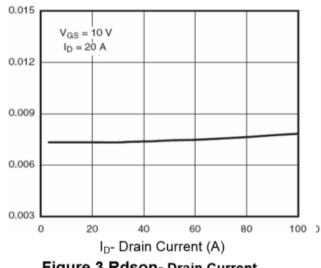
Rdson On-Resistance(m 2)



8 Ip- Drain Current (A) 6 4 T_C = 25 °C 2 T_C = 125 °C T_C = - 55 °C 0 Vgs Gate-Source Voltage (V)

Figure 1 Output Characteristics

Figure 2 Transfer Characteristics



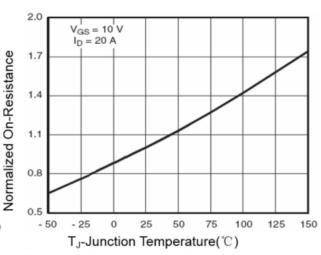
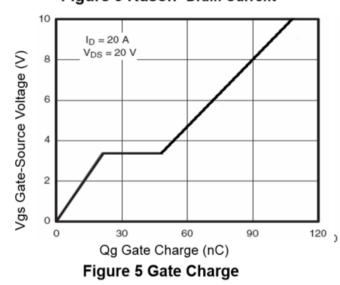


Figure 3 Rdson- Drain Current

Figure 4 Rdson-Junction Temperature



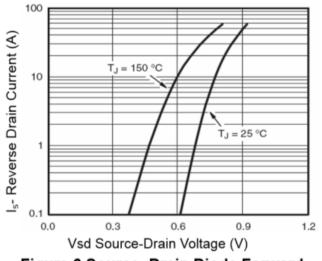
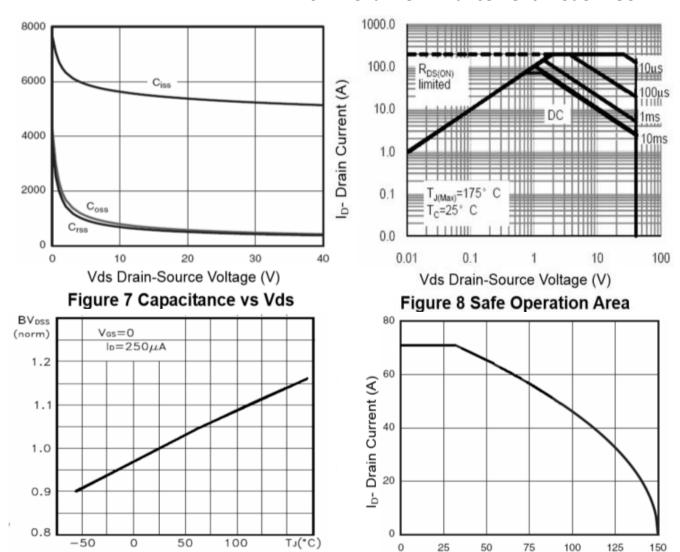


Figure 6 Source- Drain Diode Forward



C Capacitance (pF)

-40V P-Channel Enhancement Mode MOSFET



T_J-Junction Temperature(°C)

Figure 9 BV_{DSS} vs Junction Temperature

Figure 10 ID Current Derating vs Junction Temperature

T_J-Junction Temperature(°C)

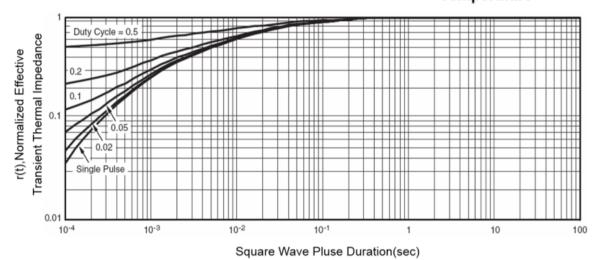
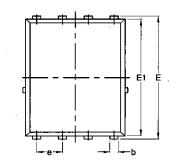
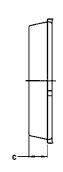


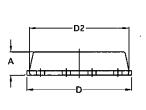
Figure 11 Normalized Maximum Transient Thermal Impedance

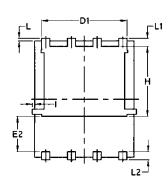


Package Mechanical Data-DFN5*6-8L-JQ Single









		Com	ımon		
Symbol	mm		Inch		
	Mim	Max	Min	Max	
Α	1.03	1.17	0.0406	0.0461	
b	0.34	0.48	0.0134	0.0189	
С	0.824	0.0970	0.0324	0.082	
D	4.80	5.40	0.1890	0.2126	
D1	4.11	4.31	0.1618	0.1697	
D2	4.80	5.00	0.1890	0.1969	
E	5.95	6.15	0.2343	0.2421	
E1	5.65	5.85	0.2224	0.2303	
E2	1.60	/	0.0630	/	
е	1.27	BSC	0.05	BSC	
L	0.05	0.25	0.0020	0.0098	
L1	0.38	0.50	0.0150	0.0197	
L2	0.38	0.50	0.0150	0.0197	
Н	3.30	3.50	0.1299	0.1378	
I	/	0.18	/	0.0070	





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AP80P04NF

-40V P-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2020/10/8	Initial release

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